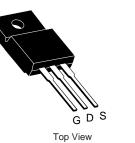
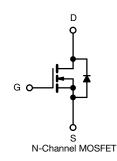


## K2529-VB Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT	DUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>			
60	0.005 at V <sub>GS</sub> = 10 V	120			
00	0.013 at V <sub>GS</sub> = 4.5 V	95			

#### TO-220 FULLPAK





#### FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:



ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> =	25 C, unless othe				
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current /T 175 °C\b	T <sub>C</sub> = 25 °C		120		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C		95 <sup>a</sup>		
Pulsed Drain Current		I <sub>DM</sub>	300	А	
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>	70 <sup>a</sup>		
Avalanche Current	I <sub>AS</sub>	50			
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ	
Movimum Power Discipation	T <sub>C</sub> = 25 °C	P <sub>D</sub> 136		w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maulanum lumation to Ambianta	t ≤ 10 sec	R <sub>thJA</sub>	15	18	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	<b>'`</b> thJA	40	50	°C/W
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1	
Notes:			•		

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t ≤ 10 s.



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1	2	3	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50 µA		
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			А	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.005		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.010			
Drain-Source On-State Resistance <sup>b</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.015			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.013			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			5650			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz		1120		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			525		1	
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$		15	25		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 50 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		35	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)		·			
Pulsed Current	I <sub>SM</sub>			300		А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	

Notes:

a. For design aid only; not subject to production testing.

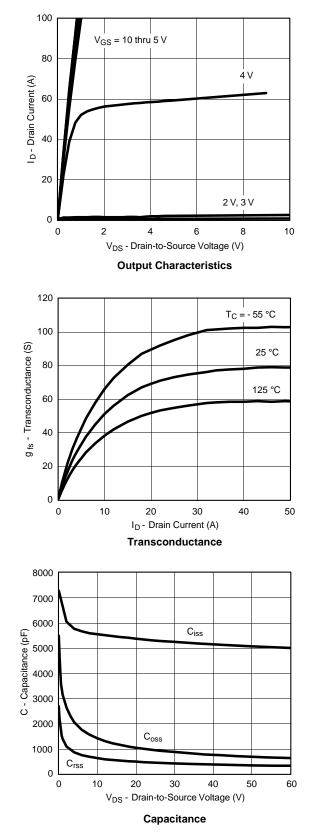
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

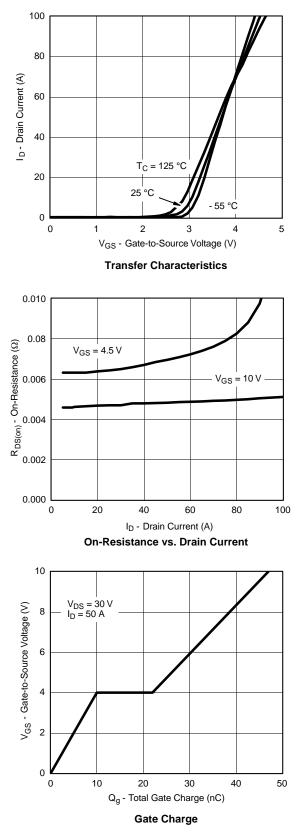
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



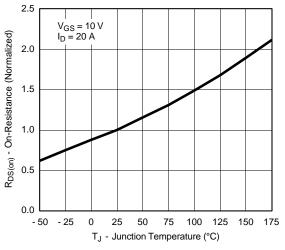




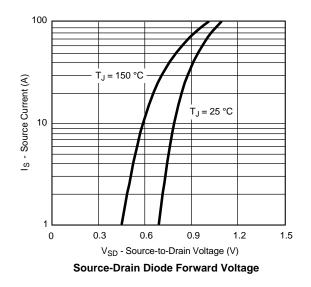




### TYPICAL CHARACTERISTICS (25 °C unless noted)

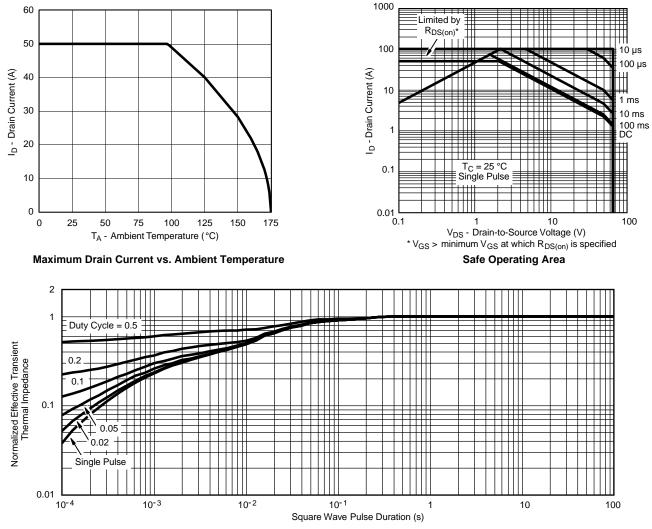


**On-Resistance vs. Junction Temperature** 





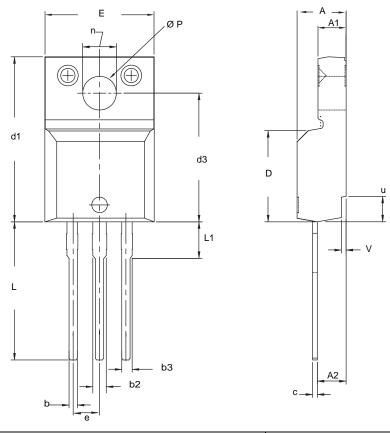
#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



#### **TO-220 FULLPAK (HIGH VOLTAGE)**



DIM.	MILLI	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØP	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet  $C_{pk} > 1.33$ . 4. All dimensions include burrs and plating thickness. 5. No chipping or package damage.



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